

ABSTRACT OF THE DISCLOSURE

An apparatus and a method for electroplating for forming a metal film by an electroplating method. The apparatus comprises a plating bath provided in a non-oxidative atmosphere, and in the method, an article to be plated is immersed in a plating bath through a non-oxidative atmosphere.

Fig. 1C

CURRENT CONCENTRATION

Fig. 3

WAFER FRONT SURFACE

WAFER BACK SURFACE

Fig. 5

Ar GAS

A

EVACUATION